

11A, 400V, 0.550 Ohm, N-Channel Power MOSFET

This advanced power MOSFET is designed, tested, and guaranteed to withstand a specified level of energy in the breakdown avalanche mode of operation. These are N-Channel enhancement mode silicon gate power field effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers, and drivers for high power bipolar switching transistors requiring high speed and low gate drive power. They can be operated directly from integrated circuits.

Formerly developmental type TA17424.

Ordering Information

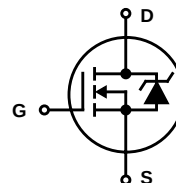
PART NUMBER	PACKAGE	BRAND
IRFP340	TO-247	IRFP340

NOTE: When ordering, include the entire part number.

Features

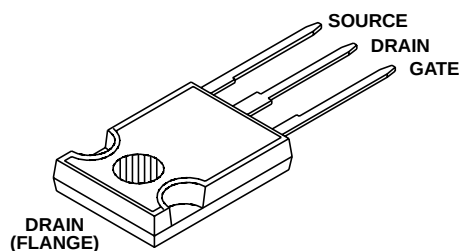
- 11A, 400V
- $r_{DS(ON)} = 0.550\Omega$
- Single Pulse Avalanche Energy Rated
- SOA is Power Dissipation Limited
- Nanosecond Switching Speeds
- Linear Transfer Characteristics
- High Input Impedance
- Related Literature
 - TB334 "Guidelines for Soldering Surface Mount Components to PC Boards"

Symbol



Packaging

JEDEC STYLE TO-247



IRFP340

Absolute Maximum Ratings $T_C = 25^{\circ}\text{C}$, Unless Otherwise Specified

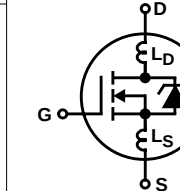
	IRFP340	UNITS
Drain to Source Voltage (Note 1)	V_{DS} 400	V
Drain to Gate Voltage ($R_{GS} = 20\text{k}\Omega$) (Note 1)	V_{DGR} 400	V
Continuous Drain Current	I_D 11	A
$T_C = 100^{\circ}\text{C}$	I_D 6.8	A
Pulsed Drain Current (Note 3)	I_{DM} 44	A
Gate to Source Voltage	V_{GS} ± 20	V
Maximum Power Dissipation	P_D 150	W
Linear Derating Factor	1.2	W/ $^{\circ}\text{C}$
Single Pulse Avalanche Energy Rating (Note 4)	E_{AS} 480	mJ
Operating and Storage Temperature	T_J, T_{STG} -55 to 150	$^{\circ}\text{C}$
Maximum Temperature for Soldering		
Leads at 0.063in (1.6mm) from Case for 10s	T_L 300	$^{\circ}\text{C}$
Package Body for 10s, See Techbrief 334	T_{pkg} 260	$^{\circ}\text{C}$

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

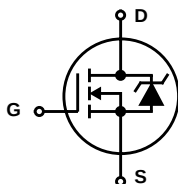
1. $T_J = 25^{\circ}\text{C}$ to 125°C .

Electrical Specifications $T_C = 25^{\circ}\text{C}$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D = 250μA (Figure 10)		400	-	-	V
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250μA		2.0	-	4.0	V
Zero-Gate Voltage Drain Current	I _{DSS}	V _{DS} = Rated BV _{DSS} , V _{GS} = 0V		-	-	25	μA
		V _{DS} = 0.8 x Rated BV _{DSS} , V _{GS} = 0V, T _J = 125°C		-	-	250	μA
On-State Drain Current (Note 2)	I _{D(ON)}	V _{DS} > I _{D(ON)} x r _{DS(ON)MAX} , V _{GS} = 10V		11	-	-	A
Gate to Source Leakage	I _{GSS}	V _{GS} = ±20V		-	-	±100	nA
Drain to Source On Resistance (Note 2)	r _{DS(ON)}	V _{GS} = 10V, I _D = 5.5A (Figures 8, 9)		-	0.47	0.55	Ω
Forward Transconductance (Note 2)	g _{fs}	V _{DS} ≥ 50V, I _D = 5.5A (Figure 12)		6.1	9.1	-	S
Turn-On Delay Time	t _{d(ON)}	V _{DD} = 200V, I _D ≈ 11A, R _{GS} = 9.1Ω, R _L = 17.4Ω MOSFET Switching Times are Essentially Independent of Operating Temperature		-	14	21	ns
Rise Time	t _r			-	27	41	ns
Turn-Off Delay Time	t _{d(OFF)}			-	50	75	ns
Fall Time	t _f			-	24	36	ns
Total Gate Charge (Gate to Source + Gate to Drain)	Q _{g(TOT)}	V _{GS} = 10V, I _D = 10A, V _{DS} = 0.8 x Rated BV _{DSS} , I _{g(REF)} = 1.5mA (Figure 14) Gate Charge is Essentially Independent of Operating Temperature		-	41	63	nC
Gate to Source Charge	Q _{gs}			-	6.0	-	nC
Gate to Drain “Miller” Charge	Q _{gd}			-	23	-	nC
Input Capacitance	C _{ISS}	V _{GS} = 0V, V _{DS} = 25V, f = 1.0MHz (Figure 11)		-	1250	-	pF
Output Capacitance	C _{OSS}			-	300	-	pF
Reverse-Transfer Capacitance	C _{RSS}			-	80	-	pF
Internal Drain Inductance	L _D	Measured from the Drain Lead, 6mm (0.25in) from the Package to the Center of the Die		-	5.0	-	nH
Internal Source Inductance	L _S	Measured from the Source Lead, 6mm (0.25in) from Header to the Source Bonding Pad		-	12.5	-	nH
Junction to Case	R _{θJC}			-	-	0.83	oC/W
Junction to Ambient	R _{θJA}	Free Air Operation		-	-	30	oC/W

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Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Continuous Source to Drain Current	I _{SD}	Modified MOSFET Symbol Showing the Integral Reverse P-N Junction Diode		-	-	11	A
Pulse Source to Drain Current (Note 3)	I _{SDM}			-	-	44	A
Source to Drain Diode Voltage (Note 2)	V _{SD}	T _J = 25 ⁰ C, I _{SD} = 11A, V _{GS} = 0V (Figure 13)		-	-	2.0	V
Reverse Recovery Time	t _{rr}	T _J = 25 ⁰ C, I _{SD} = 10A, dI _{SD} /dt = 100A/μs		170	370	790	ns
Reverse Recovered Charge	Q _{RR}	T _J = 25 ⁰ C, I _{SD} = 10A, dI _{SD} /dt = 100A/μs		1.6	3.8	8.2	μC

- NOTES:
- 2. Pulse test: pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
 - 3. Repetitive rating: pulse width limited by Max junction temperature. See Transient Thermal Impedance curve (Figure 3).
 - 4. $V_{DD} = 50\text{V}$, starting $T_J = 25^{\circ}\text{C}$, $L = 7.0\text{mH}$, $R_G = 50\Omega$, peak $I_{AS} = 11\text{A}$.

Typical Performance Curves Unless Otherwise Specified

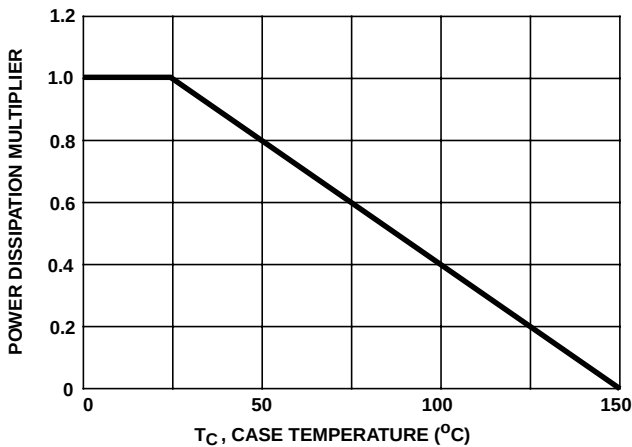


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

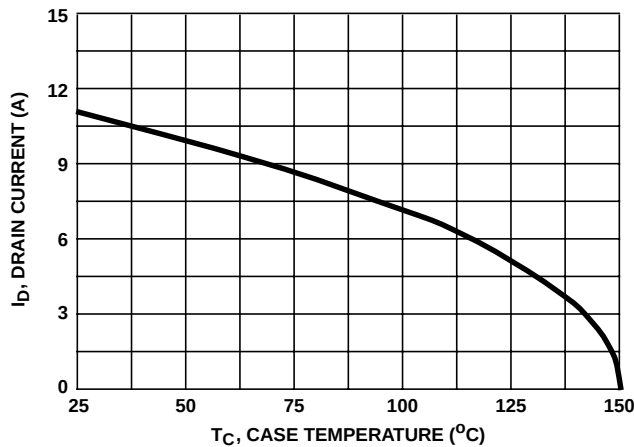


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

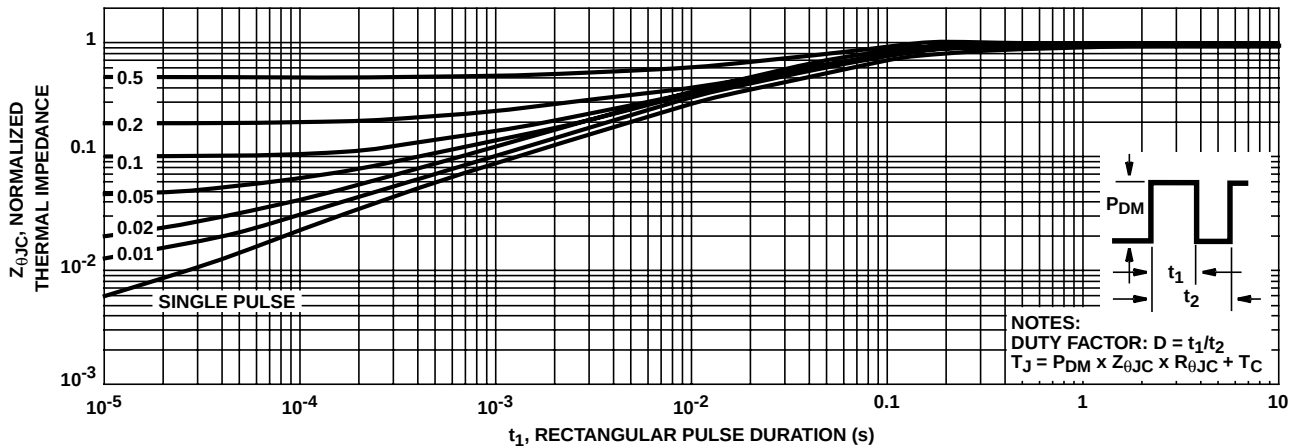


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

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Typical Performance Curves Unless Otherwise Specified (Continued)

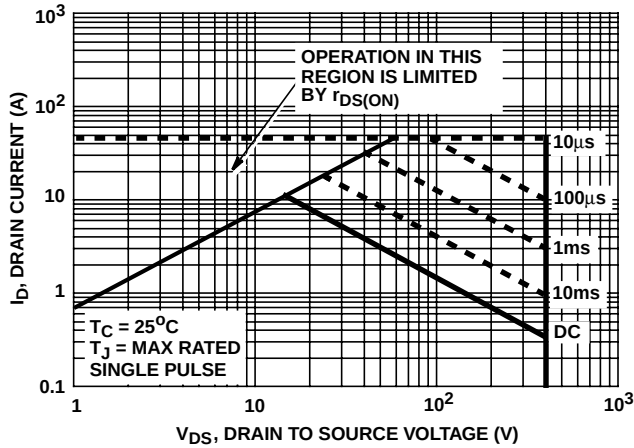


FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

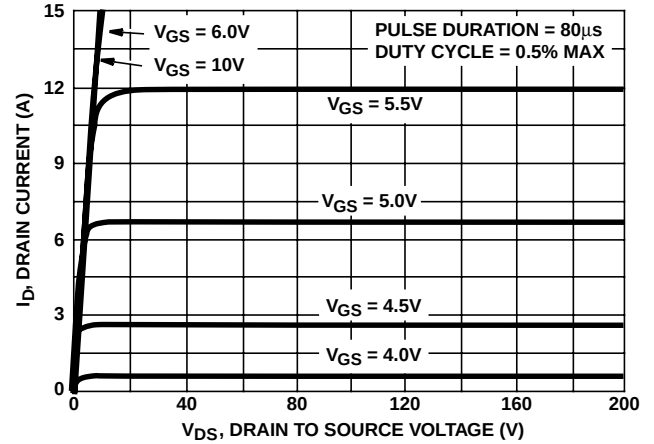


FIGURE 5. OUTPUT CHARACTERISTICS

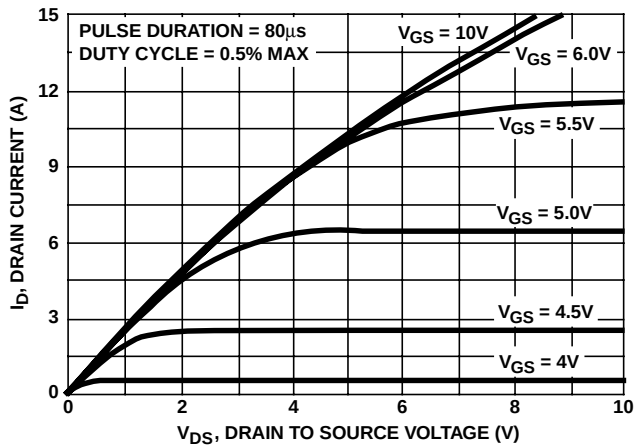


FIGURE 6. SATURATION CHARACTERISTICS

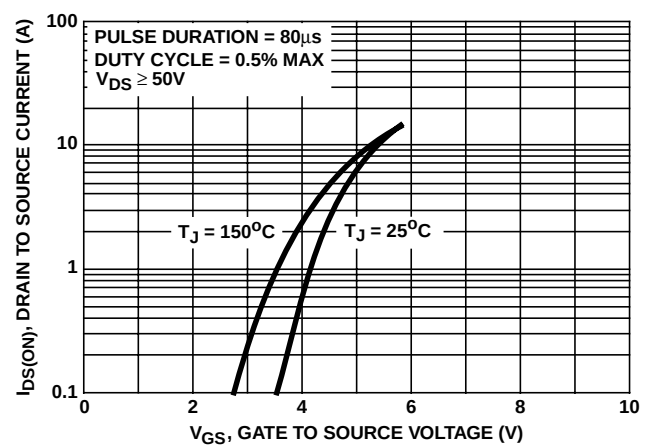


FIGURE 7. TRANSFER CHARACTERISTICS

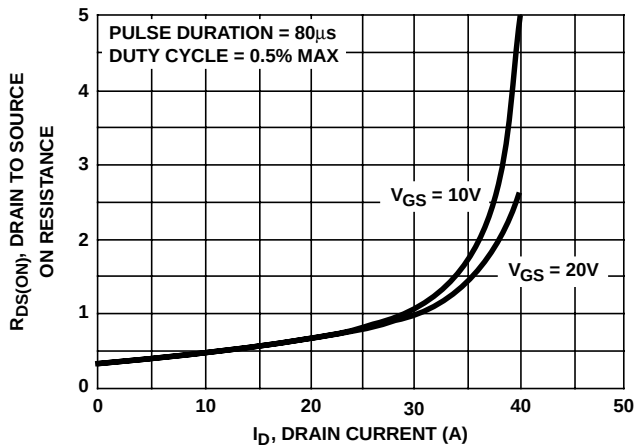


FIGURE 8. DRAIN TO SOURCE ON RESISTANCE vs. GATE VOLTAGE AND DRAIN CURRENT

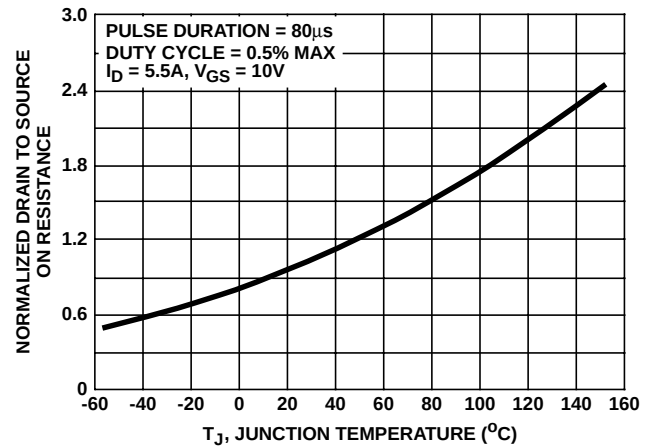


FIGURE 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs. JUNCTION TEMPERATURE

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Typical Performance Curves Unless Otherwise Specified (Continued)

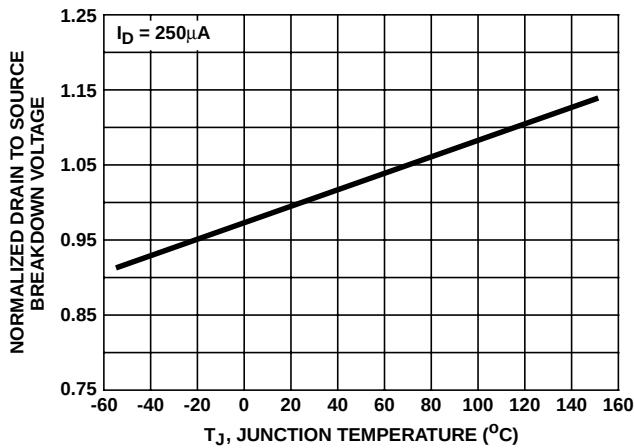


FIGURE 10. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

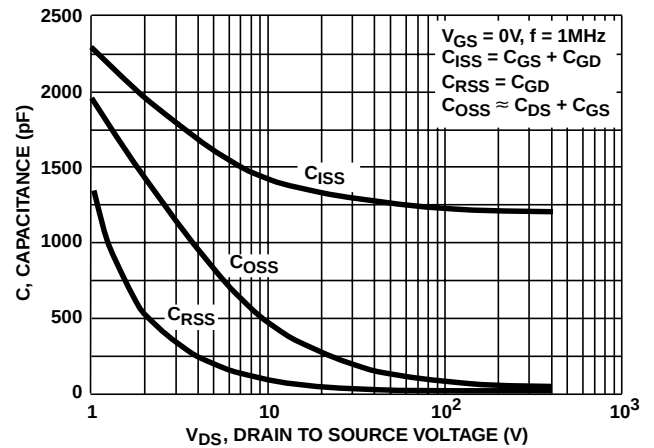


FIGURE 11. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

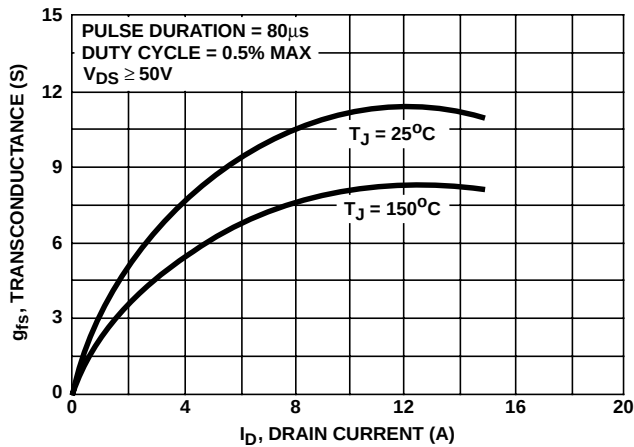


FIGURE 12. TRANSCONDUCTANCE vs DRAIN CURRENT

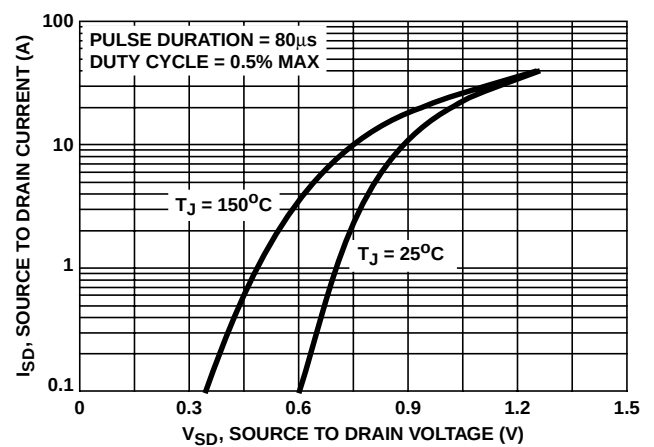


FIGURE 13. SOURCE TO DRAIN DIODE VOLTAGE

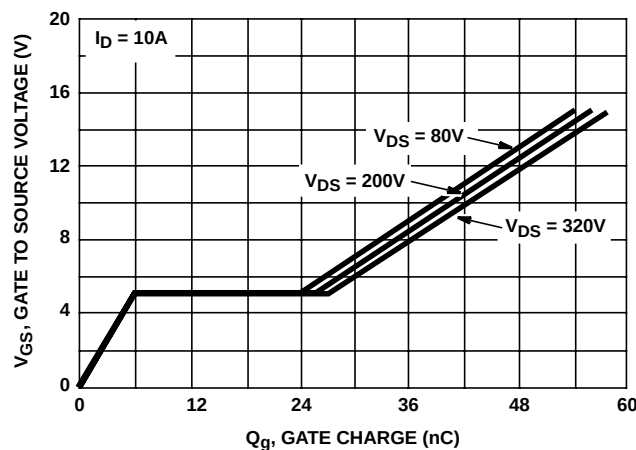


FIGURE 14. GATE TO SOURCE VOLTAGE vs GATE CHARGE

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Test Circuits and Waveforms

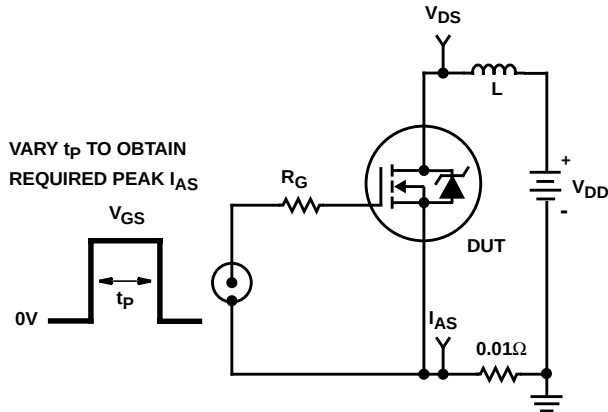


FIGURE 15. UNCLAMPED ENERGY TEST CIRCUIT

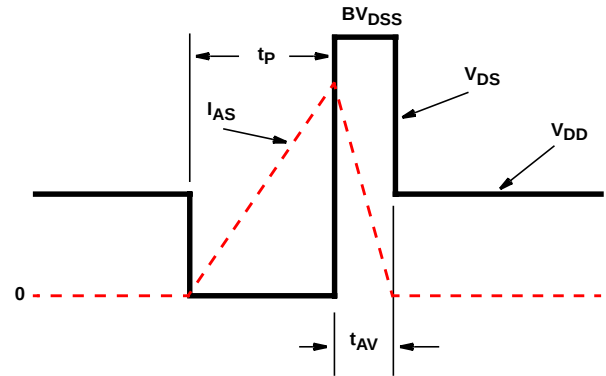


FIGURE 16. UNCLAMPED ENERGY WAVEFORMS

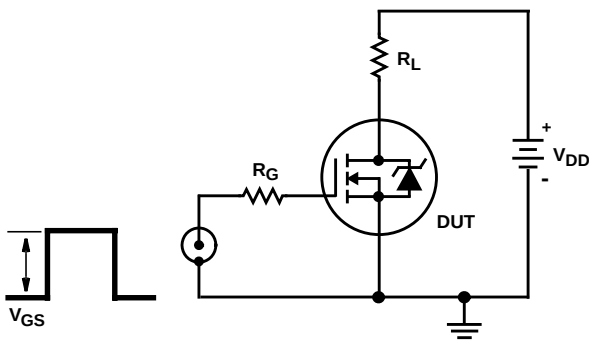


FIGURE 17. SWITCHING TIME TEST CIRCUIT

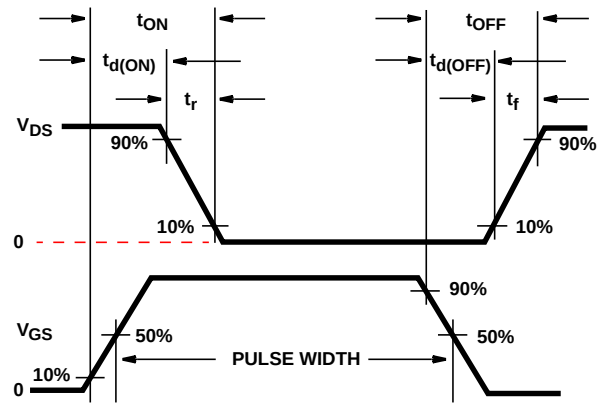


FIGURE 18. RESISTIVE SWITCHING WAVEFORMS

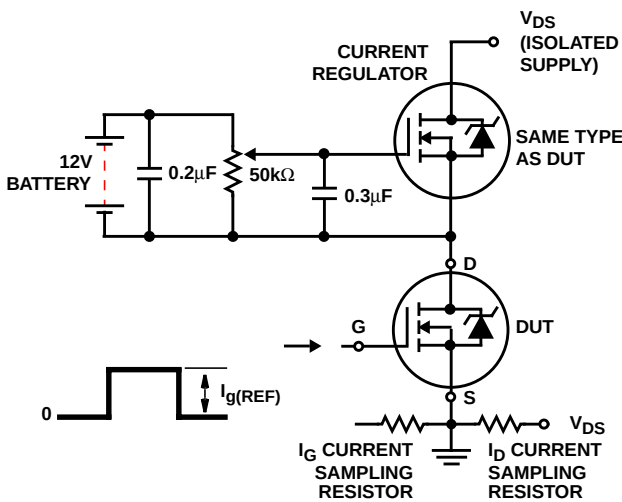


FIGURE 19. GATE CHARGE TEST CIRCUIT

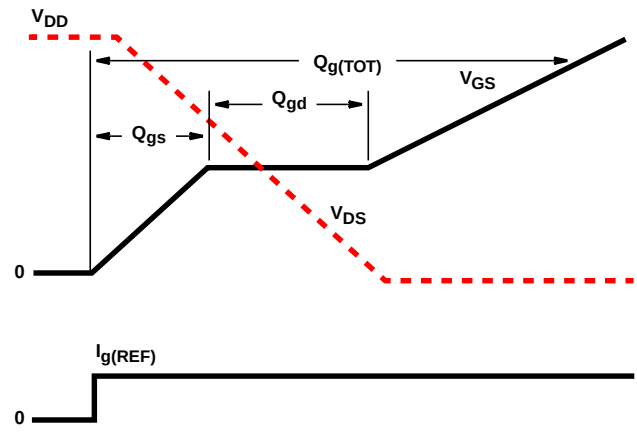


FIGURE 20. GATE CHARGE WAVEFORMS

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